

**PRODUCTION DATA SHEET** 

#### **DESCRIPTION**

The LX5255 is a Low Voltage Differential (LVD) terminator designed to comply with the LVD termination specification in the SPI-4 document. The LX5255 is specifically designed for LVD only applications. Because the LX5255 supports only LVD, it has lower output capacitance than multimode terminators such as the LX5250.

The LX5255 utilizes an industry standard LVD architecture. The individual high bandwidth drivers maximize channel separation, reduce channel-to-channel noise and cross talk to insure Ultra320 performance.

When the LX5255 is enabled, the Differential Sense (DIFSENS) pin

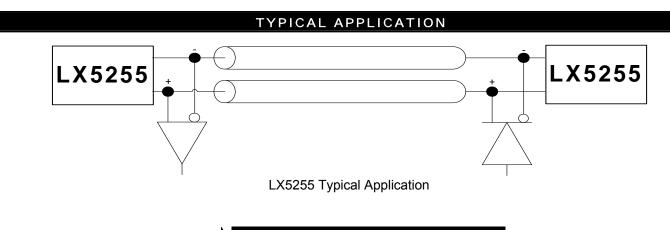
supplies a voltage between 1.2V and 1.4V. In application, the terminator DIFFB input is connected to the system DIFSENS line. If there are no single ended or High Voltage Differential (HVD) devices attached to the system, the LVD output will be enabled. If the DIFSENS line is LOW, indicating a single ended device, the LX5255 output will be HiZ. If the DIFSENS line is HIGH, indicating a HVD device, the LX5255 output will be HiZ.

The LX5255 has a TTL compatible sleep/disable mode. Applying a logic HIGH to the DISC pin puts the LX5255 in sleep mode. During sleep mode, power dissipation is reduced to a meager  $5\mu A$  while also placing all outputs and the DIFSENS function in a HiZ state.

#### **KEY FEATURES**

- Compliant with SPI-2 (Ultra2), SPI-3 (Ultra160), and SPI-4 (Ultra320)
- 2.5pF Maximum Disabled Output Capacitance
- Fast Response, No External Capacitors Required
- 5µA Supply Current in Disconnect Mode
- 30mA Supply During Normal Operation
- Logic Command Disconnects All Termination Lines
- DIFSENS Line Driver
- Current Limit and Thermal Protection
- Pin Compatible With Unitrode UCC5640

**IMPORTANT:** For the most current data, consult *MICROSEMI*'s website: http://www.microsemi.com





Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX5255CPW-TR)



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#### ABSOLUTE MAXIMUM RATINGS

Term Power (V <sub>TERM</sub> )	0.3V to 7V
Signal Line Voltage	0.3V to 7V
Differential Voltage	0.3V to 7V
Operating Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
Peak Package Solder Reflow Temperature (40 second maximum exposure)	

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

#### THERMAL DATA

PW 24L TSSOP

THERMAL RESISTANCE-JUNCTION TO AMBIENT,  $\theta_{JA}$ 

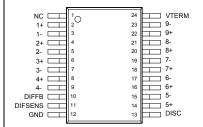
100°C/W

Junction Temperature Calculation:  $T_J = T_A + (P_D x \theta_{JA})$ .

The  $\theta_{JA}$  numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.  $\theta_{JA}$  can vary significantly depending on mounting technique. (See Application Notes Section: Thermal considerations)

#### DIFFB/POWER UP/POWER DOWN FUNCTION TABLE **Outputs** Quiescent **DIFFB** DISC Current **Status Type** L L < 0.5V Disable HI-Z 8mA 0.7V to 1.9V Enable LVD 30mA H > 2.4V Disable HI-Z L 8mA HI-Z H or Open Χ Disable 10μΑ

## PACKAGE PIN OUT



PW PACKAGE (Top View) NC – No Internal Connection

RoHS / Pb-free 100% Matte Tin Lead Finish

#### RECOMMENDED MAX OPERATING CONDITIONS

Parameter		LX5255			Units
Faranietei	Symbol	Min	Тур	Max	Ullits
VTerm	$V_{TERM}$	2.7		5.25	V
Signal Line Voltage		0		5.0	V
Disconnect Input Voltage		0		$V_{TERM}$	V
Operating Junction Temperature	TJ	0		70	°C



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#### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified, the following specifications apply over the operating ambient temperature  $0^{\circ}\text{C} \le T_{\text{A}} \le 70^{\circ}\text{C}$ , VTerm = 3.3V, and DISCONNECT = 0V.

	Parameter	Symbol	Test Conditions	LX5255			Units	
	Faranieter	Symbol	rest conditions	Min	Тур	Max	Units	
•	LVD Terminator Section							
	VTerm Supply Current	I <sub>cc</sub>	All term lines open DISCONNECT > 2.0V		30 5	35 20	mA µA	
	Common Mode Voltage	V <sub>CM</sub>		1.125	1.25	1.375	V	
	Offset Voltage (Note 1)	Vos	Open circuit between (-) and (+) terminals	100	112	125	mV	
	Differential Terminator Impedance	$Z_D$	V <sub>OUT</sub> Differential = -1V to +1V	100	105	110	Ω	
	Common Mode Impedance	Z <sub>CM</sub>	0.5V to 2V	110	150	190	Ω	
	Output Capacitance (Note 2)	Co	DISCONNECT > 2.0V			3	pF	
	Mode Change Delay	t <sub>DF</sub>	DIFSENS = 1.4V to 0V	100	115	300	ms	
•	DIFSENS Section							
	DIFSENS Output Voltage	$V_{DIFF}$		1.2	1.3	1.4	V	
	DIFSENS Output Source Current	I <sub>DIFF</sub>	DIFSENS = 0V	5		15	mA	
	DIFSENS Sink Current	I <sub>SINK(DIFF)</sub>	V <sub>TERM</sub> = 2.75V	20		200	μA	
	Disconnect Section							
	Disconnect Threshold	$V_{TH}$		0.8		2.0	V	
	Input Current	I <sub>IH</sub>	DISCONNECT = 0V			10	μA	

Note 1: Open Circuit failsafe voltage. Note 2: Guaranteed by design.



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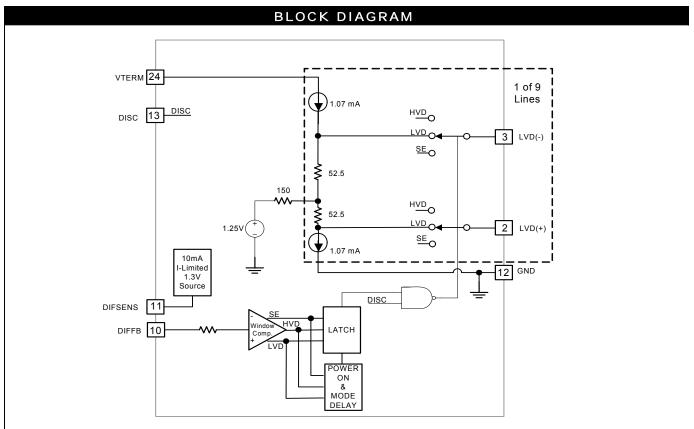


Figure 1 – LX5255CPW Block Diagram

FUNCTIONAL PIN DESCRIPTION				
PIN NAME	DESCRIPTION			
1-, 2-, 3-, 4-, 5-, 6-, 7-, 8-, 9-	Negative signal termination lines for LVD mode.			
1+, 2+, 3+, 4+, 5+, 6+, 7+, 8+, 9+	Positive signal termination lines for LVD mode.			
$V_{TERM}$	Power supply pin for terminator. Connect to SCSI bus VTERM. Must be decoupled by one 4.7µF low-ESR capacitor for every three terminator devices. It is absolutely necessary to connect this pin to the decoupling capacitor through a very low impedance (big traces to PCB). Keeping distances very short from the decoupling capacitors is somewhat layout dependent and some applications may benefit from high frequency decoupling with 0.1µF capacitors at V <sub>TERM</sub> pin.			
DISC	Enables/Disables terminator. See Power Down Function Table for logic levels.			
GND	Terminator ground pin. Connect to ground.			
DIFSENS	Differential sense pin connected to system DIFFSENS line. Drives the SCSI bus DIFSENS line to 1.3V.			
DIFFB	Used to detect the SCSI bus mode (SE, LVD or HVD). Should be connected to a 4.7uF capacitor to GND, and a 50KΩ resistor to the DIFFSENS pin (see Figure 2 on page 5).			



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#### **APPLICATION PERIPHERAL** HOST TERMPOWER **TERMPOWER** VTERM 1-**VTERM** 1+ 1+ Data Lines (9) 9-9-9+ LX5255 LX5255 DISCONNECT DISCONNECT DISC DISC GND GND **DIFSENS DIFSENS** DIFFB DIFFB NC\* NC\* 50k 50k 4.7uF 4.7uF 4.7uF 4.7uF 1-VTERM VTERM 1-1+ 1+ Data Lines (9) 9-9-9+ LX5255 LX5255 DISC DISC **GND GND DIFSENS DIFSENS** DIFFB **DIFFB** VTERM 1-1-VTERM 1+ 1+ Control Lines (9) 9-9-LX5255 LX5255 DISC DISC GND **GND DIFSENS DIFSENS DIFFB** DIFFB NC' 4.7uF

Figure 2 – Suggested Microsemi LX5255 Universal Application Schematic

<sup>\*</sup> The capacitor on Pin 1 can be placed on the LX5255PCW to be pin compatible with other devices. This capacitor is not required.

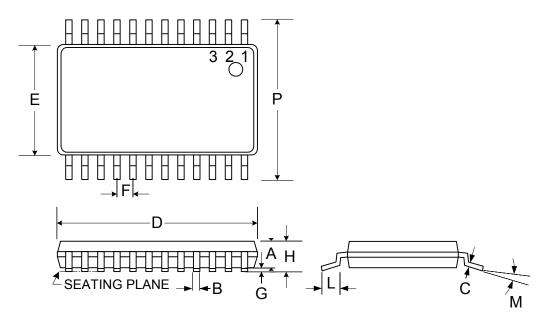


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### MECHANICAL DRAWINGS

PW

## 24-Pin Thin Small Shrink Outline (TSSOP)



Dim	MILLIMETERS		INCHES		
Dilli	MIN	MAX	MIN	MAX	
Α	0.85	0.95	0.033	0.037	
В	0.19	0.30	0.007	0.012	
С	0.09	0.20	0.0035	0.008	
D	7.70	7.90	0.303	0.311	
Е	4.30	4.50	0.169	0.177	
F	0.65 BSC		0.025 BSC		
G	0.05	0.15	0.002	0.005	
Н	_	1.10	_	.0433	
L	0.50	0.75	0.020	0.030	
М	0°	8°	0°	8°	
Р	6.25	6.55	0.246	0.256	
*LC	_	0.10	_	0.004	

## Note:

1. Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.

<sup>\*</sup> Lead Coplanarity



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NOTES

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